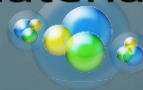




Electronics Materials Information



Photoresist, Extensions & Ancillary Materials Technology, Market & Supply Chain for Semiconductor Device Processing *A TECHCET Critical Materials Report™*

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RESEARCH METHODOLOGY

TEHCET employs subject matter experts having first-hand experience within the industries, which they analyze. Most of TEHCET's analysts have over 25 years of direct and relevant experience in their field. Our analysts survey the commercial and technical staff of IC manufacturers and their suppliers, and conduct extensive research of literature and commerce statistics to ascertain the current and future market environment and global supply risks. Combining this data with TEHCET's proprietary, quantitative wafer forecast results in a viable long-term market forecast for a variety of process materials.

REPORT SCOPE

This TECHCET Critical Materials Report provides information and market assessment of the business and technology trends associated with the Photoresist, Extension & Ancillary Materials used for semiconductor device manufacturing. Supply chain activity and dynamics, as well as supplier profiles are provided. Market drivers forcing change in the industry are looked at from a macro as well as micro viewpoint as it relates to the semiconductor industry. This report includes market statistics (market shares and revenue history and growth), business and technology drivers and challenges.

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